



Material Declaration Data Sheet

Model: **SR1600UR, SR1625UR, SR2600UR, SR2625UR Families** Manufacturer: Intel Corporation

Note: This declaration applies to all associated product codes noted on Page 2

Lead Free (Pb) Product: **Yes for 2LI**

Date: February 18, 2009

Restriction on Hazardous Substances (RoHS) Compliance

RoHS Definition

- Quantity limit of 0.1% by mass (1000PPM) for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE)
- Quantity limit of 0.01% by mass (100 PPM) for: Cadmium

Intel understands RoHS requires: Lead and other materials banned in the RoHS Directive are either (1) below all applicable substance thresholds as proposed by the EU or (2) an approved/pending exemption applies. (Note: RoHS implementing details are not fully defined and may change.)

RoHS Declaration

- 1** Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
- 2** Lead as an alloying element in steel containing up to 0.35 % lead by weight.
- 3** Lead as an alloying element in aluminum containing up to 0.4 % lead by weight.
- 4** Lead as an alloying element in copper containing up to 4 % lead by weight.
- 5** Lead in high melting temperature type solders (i.e. lead based alloys containing 85 % by weight or more lead)
- 6** Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.
- 7** Lead in electronic ceramic parts (e.g. piezoelectronic devices).
- 8** Lead used in compliant pin connector systems.
- 9** Lead as a coating material for the thermal conduction module c-ring.
- 10** Lead in optical and filter glass.
- 11** Lead in solders consisting of more than two parts for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight.
- 12** Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.
- 13** Cadmium in optical and filter glass.
- 14** Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (*) amending Directive 76/769/EEC (**) relating to restrictions on the marketing and use of certain dangerous substances and preparations.
- 15** Lead in bronze bearing shells and brushes.
- 16** Lead in printing inks for application of enamels on borosilicate glass
- 17** Cadmium in printing inks for application of enamels on borosilicate glass
- 18** Lead in Finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with NiFe lead frames and and lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with copper lead frames
- 19** Lead in solders for the soldering to machined through hole discoidal and planar array ceramic capacitors
- 20** Lead oxide in plasma display panels (PDP) and surface conduction electron emitter displays (SED) used in structural elements: notably in the front and rear glass dielectric layer, the bus electrode, the black stripe, the address electrode, the barrier ribs, the seal frit, and frit ring as well as in print pastes.
- 21** Other

Where the product is declared to meet RoHS requirements, it has been verified to be in conformance with 2002/95/EC as we currently understand the requirements. Intel has systems in place to verify conformance with all applicable environmental requirements and to the best of our knowledge the information is true and correct.

INTEL ACCEPTS NO DUTY TO UPDATE THIS DECLARATION OR TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION. INTEL SHALL NOT BE LIABLE FOR ANY DAMAGES, DIRECT OR INDIRECT, CONSEQUENTIAL OR OTHERWISE, SUFFERED BY USERS OR THIRD PARTIES AS A RESULT OF THE USERS RELIANCE ON INFORMATION IN THIS DECLARATION THAT HAS BEEN UPDATED OR CHANGED.

Product Code Information



Product Code	Description	*RoHS Exemption #
SR2600URBRP	Driskill3_3.5_BIK BRP	1, 5, 7
SR2600URLX	Driskill 3.5 BIK LX	1, 5, 7
R2625URBRP	Driskill3_2.5_BIK BRP	1, 5, 7
SR2625URLX	Driskill3_2.5_BIK_LX	1, 5, 7
SR1600URHS	Dowling3_HSBP	1, 5, 7
SR1600UR	Dowling3_Fixed	1, 5, 7
SR1625URSAS	Petrof Bay2_BIK_Active	1, 5, 7
SR1625UR	Petrof Bay2_BIK_Passive	1, 5, 7
AXXRMM3	RMM3 option (single pack)	1
ASR1625FP	PB-T Front panel option	1, 7
ASR26XXFHR	2U FH PCI-E Riser	1
ASR26XXFHLPR	2U FH PCI-E Butterfly Riser	1, 5
ASR26XXFHXR	2U PCI-X Butterfly Riser	1
AXX4GBIOMOD2	Kawela with dual giga port	1
FSR16XXRISER	1U FH PCI-E Riser	1
ASR2600FXDRV	2.5" HDD cage option	Compliant with no exemptions
ASR2600LXFANS	2U redundant fan option.	Compliant with no exemptions
BB5520UR	Urbanna Baseboard	1, 5, 7
AXX10GBIOMOD	10G IO board	1, 5
FSR1625EESPR	PB-T ELECTRICAL SPARE KIT	1, 5, 7
FSR1600EESPR	DW-T ELECTRICAL SPARE KI	1, 5, 7
FSR2600LXFAN	DR-T LX FANS SPARE,SINGLE PACK	Compliant with no exemptions
FSRTCHSPR	Chassis Spare Kit,SINGLE PACK	Compliant with no exemptions
FSR26XXEESPR	DR-T Chassis Electrical Spare Kit	1, 5, 7
FURBRIDGE	Bridge Board Spare	Compliant with no exemptions
SE24717	URBANNA, SPARE, BRD, TELCO 10P	1,4, 5, 7

* RoHS Exemption # corresponds with exemption #'s found on page 1.